DATE 26 OCT 2011

NOTES:
2. DIMENSIONS IN MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION.
4. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

**GENERIC MARKING DIAGRAM***

XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

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**DOCUMENT NUMBER:** 98AON13023D
**DESCRIPTION:** 28 LEAD TSSOP, 9.7X4.4X1.0 MM, 0.65 PITCH

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